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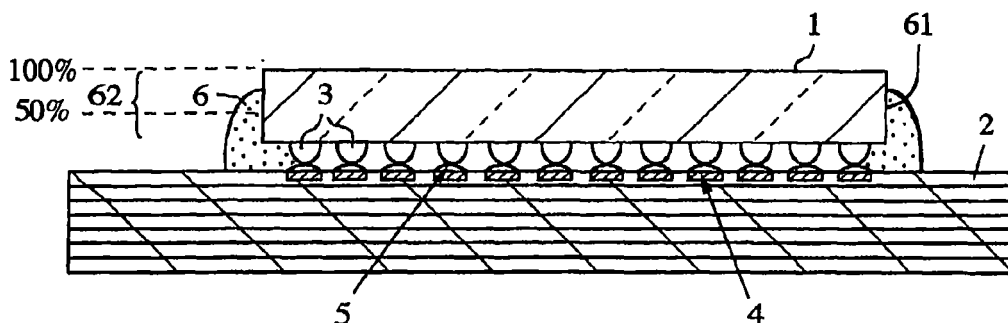
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(54) Title: CIRCUIT BOARD ASSEMBLY AND METHOD OF ATTACHING A CHIP TO A CIRCUIT BOARD



(57) Abstract: An antenna array (100) is assembled by direct attaching a flip chip transmit/receive (T/R) module (1) to an antenna circuit board (2). A fillet bond (6) is applied to the circuit board (2) and the flip chip T/R module (1) around at least a portion of the periphery of the flip chip T/R module (1).



ACTION

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